

### **Additional Information**







Resources

Accessories

**Samples** 

### **Description**

The ASMDC PPTC offers a lower profile form factor for better space saving and provides higher VDC and IHOLD rating, most robust performance compared to the competitors in the market.

### **Features & Benefits**

- Products meet applicable automotive industry standards
- Compatible with high-volume electronics assembly
- Lower Profile Comparing to the existing 2920 size ASMD
- Resettable solution against overcurrent and short-circuit
- AEC-Q200 qualified, RoHS compliant, and ISO/TS16949 certified
- Surface-mount form factor
- High Performance expertise from the world's leading resettable overcurrent protection manufacturer

- Provides wider range of form factors to enhance design flexibility
- Restores system operation after reset when fault condition is removed, thus provides safety and protection
- Able to meet most stringent requirements for the extreme harsh automotive environment
- Suitable for standard PCB assembly to enable automated mass production

### **Applications**

- Automotive and industrial transportation
- Actuators and medium motors
- Trace protection
- Harness/junction box protection
- Powered outputs
- Electronic control modules
- Telematics/Infotainment

### **Electrical Characteristics**

Part	Ordering	I <sub>H</sub> (A)@	I <sub>H</sub> (A)@	I <sub>T</sub>	V <sub>MAX</sub>	I <sub>MAX</sub>	P <sub>D Typ</sub>	Max Tim	e-to-trip	R <sub>MIN</sub>	R <sub>1MAX</sub>	R <sub>aMAX</sub>
Number	Part Number	(R <sub>1MAX</sub> )	(R <sub>aMAX</sub> )	(A)	(V <sub>DC</sub> )	(A)	(W)	(A)	(s)	(Ω)	(Ω)	(Ω)
				Α	SMDC - 2	24-60V						
ASMDC030F	RF4571-000	0.30	0.30	0.60	60	10	1.50	1.50	3.00	0.30	3.40	3.40
ASMDC050F	RF4572-000	0.50	0.50	1.00	60	10	1.50	2.50	4.00	0.15	1.20	1.20
ASMDC075F	RF4573-000	0.75	0.75	1.50	33	40	1.50	8.00	0.30	0.10	0.61	0.61
ASMDC125F/33	RF4574-000	1.25	1.25	2.50	33	40	1.50	8.00	2.00	0.04	0.25	0.25
ASMDC185F/33	RF4575-000	1.85	1.85	3.70	33	40	1.70	8.00	2.50	0.05	0.15	0.15
ASMDC300F/24	RF4576-000	3.00	3.00	6.00	24	40	1.70	8.00	5.00	0.015	0.072	0.072

### Notes:

: Hold current: maximum current device will pass without interruption in 25°C, unless otherwise specified : Trip current: minimum current that will switch the device from low-resistance to high-resistance in 25°C still air, unless otherwise specified

V<sub>MAX</sub>: Maximum voltage device can withstand without damage at rated current.

IMAX : Maximum fault current device can withstand without damage at rated voltage

: Power dissipated from device when in the tripped state in 25°C still air, unless otherwise specified.

R<sub>MIN</sub>: Minimum resistance of device as supplied at 25°C, unless otherwise specified.

R<sub>IMAX</sub>: Maximum resistance of device when measured one hour post reflow, unless otherwise specified.

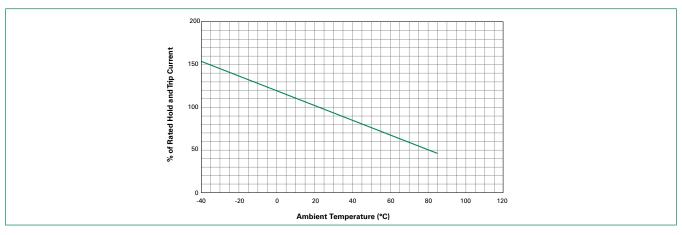
Ramax: Maximum functional resistance of device after being subjected to the stresses described in PS400 at 25°C, unless otherwise specified.



### **Temperature Rerating**

Maximum Ambient Temperature										
Part Number	-40°C	-20°C	0°C	20°C	25°C	40°C	50°C	60°C	70°C	85°C
	Hold Current (A)									
				ASMDC -	24-60V					
ASMDC030F	0.49	0.43	0.37	0.31	0.30	0.25	0.22	0.19	0.16	0.12
ASMDC050F	0.86	0.75	0.65	0.54	0.50	0.43	0.37	0.32	0.26	0.18
ASMDC075F	1.17	1.04	0.90	0.77	0.75	0.64	0.57	0.50	0.44	0.34
ASMDC125F/33	2.02	1.78	1.55	1.31	1.25	1.08	0.96	0.84	0.72	0.54
ASMDC185F/33	2.83	2.50	2.20	1.85	1.74	1.53	1.37	1.22	1.04	0.80
ASMDC300F/24	4.70	4.19	3.70	3.17	3.00	2.66	2.41	2.20	1.90	1.50

### **Temperature Rerating Curve**



### Typical Time-to-Trip Curves at 25°C

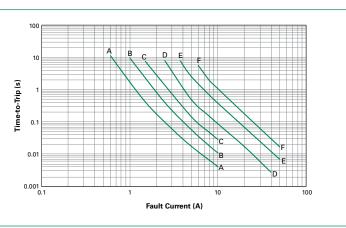


A = ASMDC030FB = ASMDC050F

C = ASMDC075F

D = ASMDC125F/33

E = ASMDC185F/33F = ASMDC300F/24





### **Physical Specifications**

Terminal Pad Material	100% Matte Tin with Nickel Underplate
Soldering Characteristics	Solderability per ANSI-J-STD-002 Category 3
Solder Heat Withstand	per IEC 60068-2-20, Test Tb, Section 5, Method 1a
Flammability	per IEC 60695-11-5 Needle Flame Test for 20 seconds
Recommended Storage Conditions	40°C max, 70% RH max; Devices May Not Meet Specified Ratings if Storage Conditions are Exceeded
Operation Temperature	-40°C~85°C

Note: See PS400 for other physical specifications.

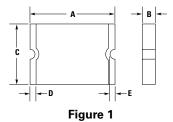
### **Environmental Specifications**

Test	Conditions	Resistance Change
Passive Aging	60°C, 1000 hrs 85°C, 1000 hrs	±3% Typical ±5% Typical
Humidity Aging	85°C, 85% R.H., 100 hrs	±1.2% Typical
Thermal Shock	85°C, -40°C 20 times	-33% Typical
Solvent Resistance	Freon Trichloroethane Hydrocarbons	No change No change No change

Note: See PS400 for other environmental specifications.

Moisture Resistance Level	Level 2a, J-STD-020
Storage Conditions	40°C max, 70% RH max; devices should remain in original sealed bags prior to use.  Devices may not meet specified values if these storage conditions are exceeded.

### **Dimension Figures**

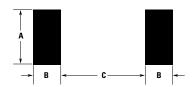


### **Dimensions**

				Dimen	nsions in Mi	llimeters (I	nches)				
Part Number	A B			В	C C			D		E	
	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
	ASMDC – 24-60V										
ASMDC030F	7.30	7.70	0.63	0.90	4.90	5.30	0.25	0.95	0.20		1
ASIVIDCUSUF	(0.287)	(0.303)	(0.025)	(0.035)	(0.193)	(0.209)	(0.010)	(0.040)	(0.008)	_	ı
ASMDC050F	7.30	7.70	0.63	0.90	4.90	5.30	0.25	0.95	0.20	<u> </u>	
ASIVIDCUSUF	(0.287)	(0.303)	(0.025)	(0.035)	(0.193)	(0.209)	(0.010)	(0.040)	(0.008)		'
ASMDC075F	7.30	7.70	0.63	0.90	4.90	5.30	0.25	0.95	0.20		1
ASMDC075F	(0.287)	(0.303)	(0.025)	(0.035)	(0.193)	(0.209)	(0.010)	(0.040)	(0.008)	_	'
A CNAD C12E F/22	7.30	7.70	0.45	0.71	4.90	5.30	0.25	0.95	0.20		1
ASMDC125F/33	(0.287)	(0.303)	(0.018)	(0.028)	(0.193)	(0.209)	(0.010)	(0.040)	(0.008)	_	
ASMDC185F/33	7.30	7.70	0.90	1.20	4.90	5.30	0.25	0.95	0.20		1
ASIVIDC 180F/33	(0.287)	(0.303)	(0.035)	(0.047)	(0.193)	(0.209)	(0.010)	(0.040)	(0.008)	_	'
A CN 4D C200E /24	7.30	7.70	0.80	1.10	4.90	5.30	0.25	0.95	0.20		1
ASMDC300F/24	(0.287)	(0.303)	(0.031)	(0.043)	(0.193)	(0.209)	(0.010)	(0.040)	(0.008)	_	'



### **Recommended Pad Layout**



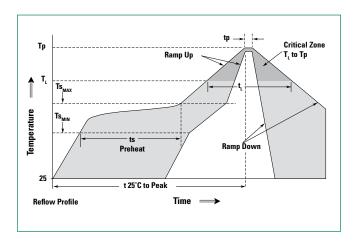
### **Packaging and Marking Information**

Part	Tape and Reel	•		Recommended Pad Layout Figures [mm (in)]				
Number	Quantity	Package	Marking	Dimension A (Min*/Nom)	Dimension B (Nom)	Dimension C (Nom)		
		A	SMDC - 24-60V					
ASMDC030F	4,000	20,000	030F	5.30 (0.209)	2.00 (0.079)	4.60 (0.18)		
ASMDC050F	4,000	20,000	050F	5.30 (0.209)	2.00 (0.079)	4.60 (0.18)		
ASMDC075F	4,000	20,000	075F	5.30 (0.209)	2.00 (0.079)	4.60 (0.18)		
ASMDC125F/33	4,000	20,000	125F	5.30 (0.209)	2.00 (0.079)	4.60 (0.18)		
ASMDC185F/33	4,000	20,000	185F 33V	5.30 (0.209)	2.00 (0.079)	4.60 (0.18)		
ASMDC300F/24	4,000	20,000	300F 24V	5.30 (0.209)	2.00 (0.079)	4.60 (0.18)		

<sup>\*</sup> These devices are intended for use in automotive applications.

### **Solder Reflow Recommendations**

Profile Feature	Pb-Free Assembly
Average ramp up rate (Ts <sub>MAX</sub> to Tp)	3°C/s max
Preheat	
• Temperature min (Ts <sub>MIN</sub> )	150°C
Temperature max (Ts <sub>MAX</sub> )	200°C
• Time (ts <sub>MIN</sub> to ts <sub>MAX</sub> )	60-120 s
Time maintained above:	
• Temperature (T <sub>L</sub> )	217°C
• Time (t <sub>L</sub> )	60-150 s
Peak/Classification temperature (Tp)	260°C
Time within 5°C of actual peak temperature	
Time (tp)	30 s max
Ramp down rate	3°C/s max
Time 25°C to peak temperature	8 min max



Note: All temperatures refer to topside of the package, measured on the package body surface.

### **Solder Reflow**

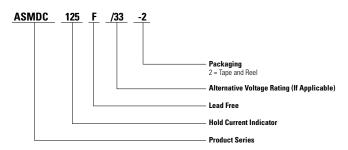
- Recommended reflow method: IR, hot air, nitrogen.
- Recommended maximum paste thickness: 0.25mm (0.010in)
- Devices can be cleaned using standard methods and aqueous solvents.
- Experience has shown the optimum conditions for forming acceptable solder fillets occur when a reasonable amount of solder paste is placed underneath each device's termination. As such, we request that customers comply with our recommended solder pad layouts.
- Customer should validate that the solder paste amount and reflow recommendations meet its application.
- We request that customer board layouts refrain from placing raised features (e.g. vias, nomenclature, traces, etc.) underneath PolySwitch devices. It is possible that raised features could negatively impact solderability performance of our devices.

### Rework

Standard industry practices. (Please also avoid direct contact to the device.)



### **Part Ordering Number System**



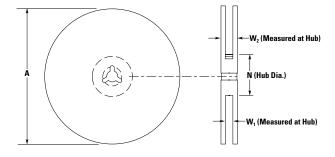
### **Tape and Reel Diagrams**

Figure 1

# Figure 2 Carrier Tape

### **Tape and Reel Specifications**

	ASMDC EIA 481-1							
Description	ASMDC030F ASMDC050F ASMDC075F ASMDC125F/33	ASMDC185F/33 ASMDC300F/24						
W	$16.0 \pm 0.30$	$16.0 \pm 0.30$						
$P_0$	$4.0 \pm 0.10$	$4.0 \pm 0.10$						
P <sub>1</sub>	$8.0 \pm 0.10$	$8.0 \pm 0.10$						
$P_2$	$2.0 \pm 0.10$	$2.0 \pm 0.10$						
$A_0$	$5.5 \pm 0.1$	5.35 ± 0.1						
$B_0$	$7.9 \pm 0.1$	$7.85 \pm 0.1$						
B <sub>1</sub> max	12.1	12.1						
$D_0$	1.5 + 0.10/00	1.5 + 0.10/00						
F	$7.50 \pm 0.10$	$7.50 \pm 0.10$						
E <sub>1</sub>	$1.75 \pm 0.10$	1.75 ± 0.10						
E <sub>2</sub> min	14.25	14.25						
T max	0.35	0.35						
T <sub>1</sub> max	0.1	0.1						
K <sub>o</sub>	$0.9 \pm 0.1$	1.45 ± 0.1						
A max	330	330						
N min	50	50						
$\mathbf{W}_{1}$	16.4 + 2.0/00	16.4 + 2.0/00						
W <sub>2</sub> max	22.4	22.4						



### Warning

- Users should independently evaluate the suitability of and test each product selected for their own application.
- Operation beyond the maximum ratings or improper use may result in device damage and possible electrical arcing and flame.
- These devices are intended for protection against damage caused by occasional overcurrent or overtemperature fault conditions and should not be used when repeated fault conditions or
- Contamination of the PPTC material with certain silicone-based oils or some aggressive solvents can adversely impact the performance of the devices.
- Device performance can be impacted negatively if devices are handled in a manner inconsistent with recommended electronic, thermal, and mechanical procedures for electronic
- PPTC devices are not recommended for installation in applications where the device is constrained such that its PTC properties are inhibited, for example in rigid potting materials or in rigid housings, which lack adequate clearance to accommodate device expansion.
- Operation in circuits with a large inductance can generate a circuit voltage (Ldi/dt) above the rated voltage of the device.

Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at <a href="https://www.littelfuse.com/disclaimer-electronics">www.littelfuse.com/disclaimer-electronics</a>.

